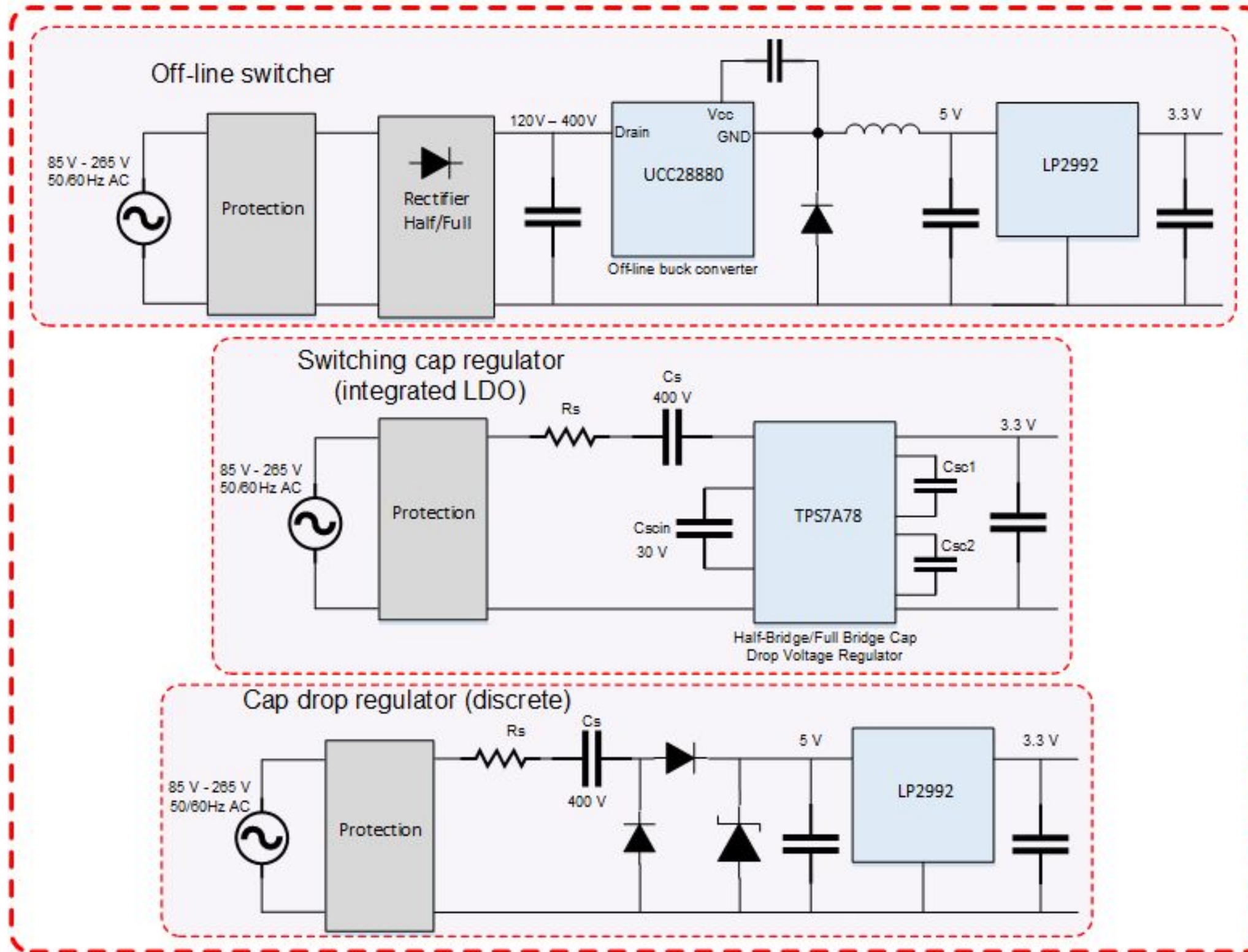


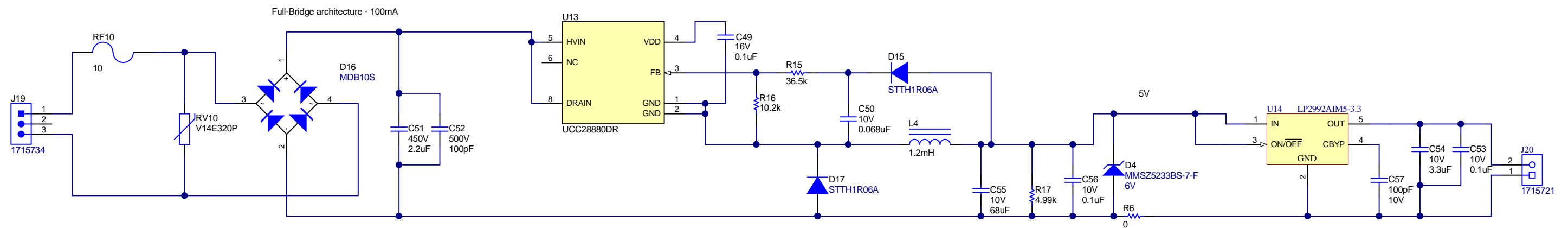
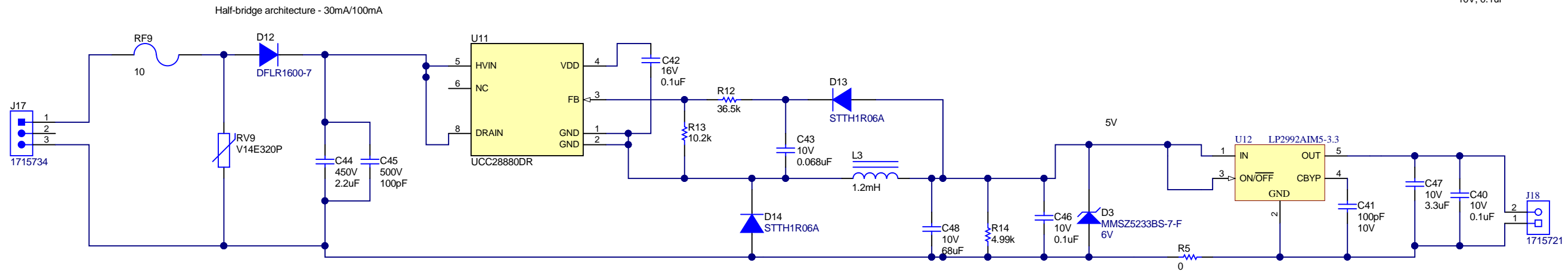
Revision History

Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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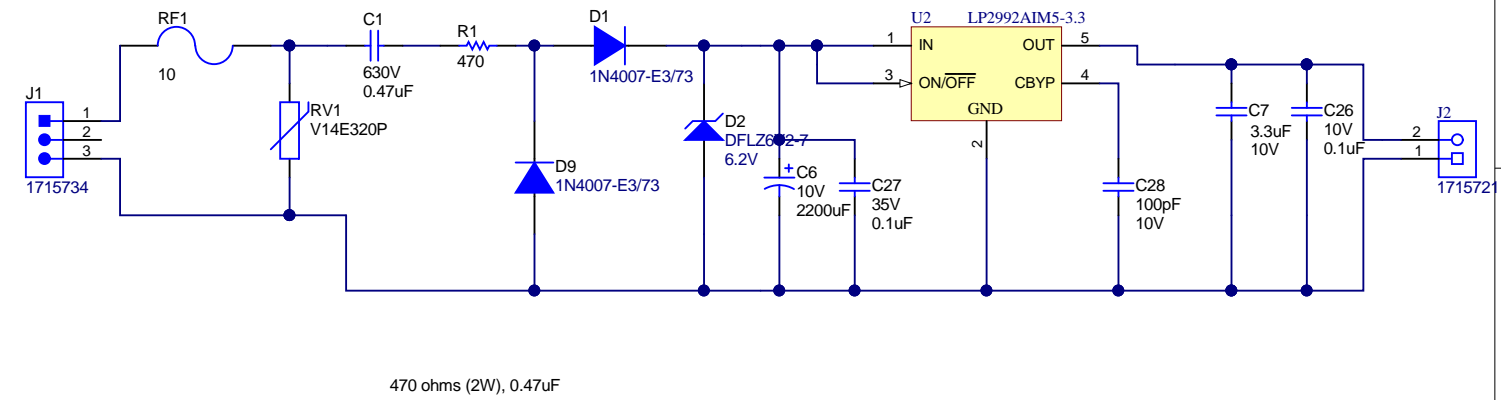
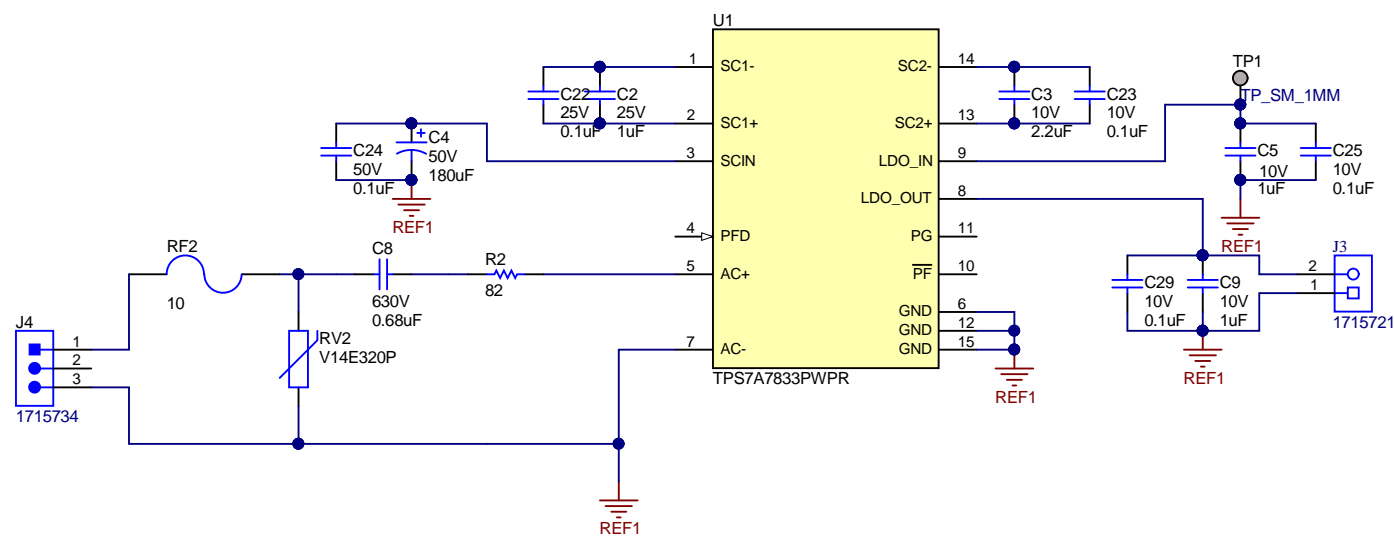
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TID #: TIDA-010060	Project Title: Non-isolated AC-DC architectures	
Number: TIDA-010060	Rev: E1	Sheet Title:
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 1 of 3
Drawn By:	File: AC_DC_CoverSheet.SchDoc	Size: B
Engineer: Prasanna Rajagopal	Contact: http://www.ti.com/support	



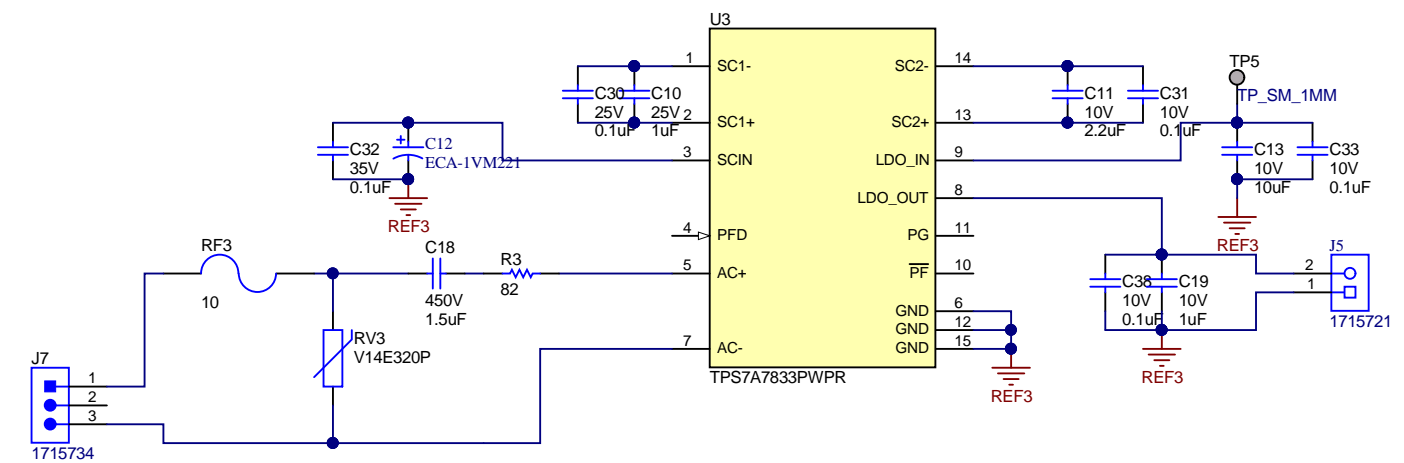
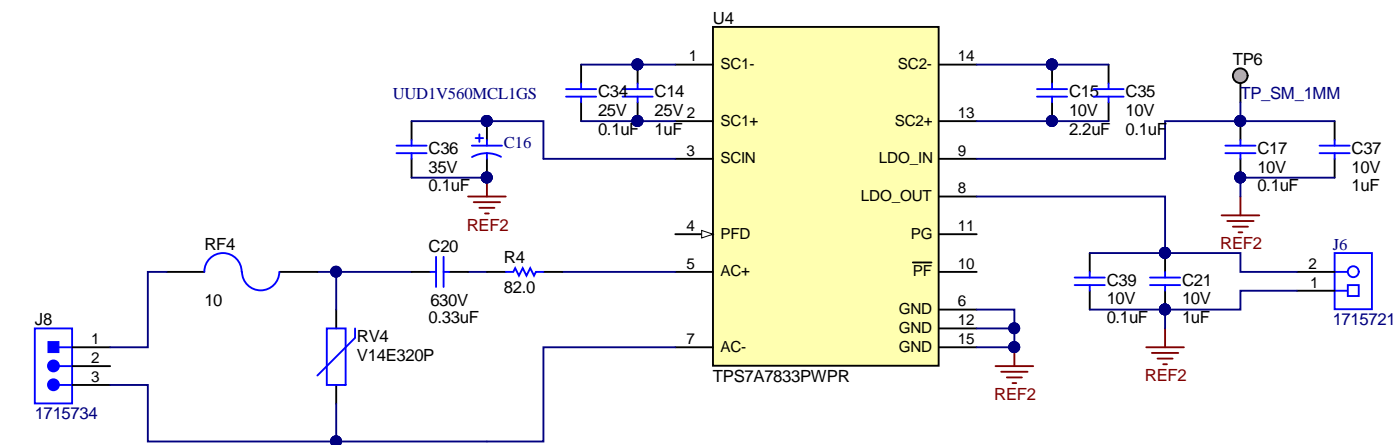
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TID #: TIDA-010060	Project Title: Non-isolated AC-DC architectures	
Number: TIDA-010060	Rev: E1	Sheet Title:
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 2 of 3
Drawn By:	File: Offline_buck.SchDoc	Size: B
Engineer: Prasanna Rajagopal	Contact: http://www.ti.com/support	

Half-bridge architecture - 30mA



Full-Bridge architecture - 30mA



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TID #: TIDA-010060	Project Title: Non-isolated AC-DC architectures	
Number: TIDA-010060	Rev: E1	Sheet Title:
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 2 of 3
Drawn By:	File: Cap Drop.SchDoc	Size: B
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Number: TIDA-010060 Rev: E1	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 2 of 3
Drawn By:	File: AC_DC_BlankSheet.SchDoc	Size: B
Engineer: Prasanna Rajagopal	Contact: http://www.ti.com/support	



H9 SJ-5303 (CLEAR) H10 SJ-5303 (CLEAR) H11 SJ-5303 (CLEAR) H12 SJ-5303 (CLEAR)

FID1 FID2 FID3

PCB Number: TIDA-010060
PCB Rev: E1

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You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You should delete this note too.

Variant/Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
THT-14-423-10
Size: 0.65" x 0.20 "

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable:	Designed for: Public Release	Mod. Date: 2/26/2019
TID #: TIDA-010060	Project Title: Non-isolated AC-DC architectures	
Number: TIDA-010060 Rev: E1	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 3 of 3
Drawn By:	File: AC_DC_Hardware.SchDoc	Size: B
Engineer: Prasanna Rajagopal	Contact: http://www.ti.com/support	

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